



**COPY**

Docket No. 60173 (71987)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

APPLICANT: C. Huang

U.S. SERIAL NO: 10/696,198

EXAMINER: H. Trinh

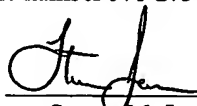
FILED: October 28, 2003

GROUP: 2814

FOR: MULTI-CHIP PACKAGE DEVICE WITH HEAT SINK AND  
FABRICATION METHOD THEREOF

**CERTIFICATE OF FACSIMILE TRANSMISSION**

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted by facsimile to the U.S. Patent & Trademark Office by facsimile number 571-273-8300 on January 13, 2006.

By:   
Steven M. Jensen

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir/Madam:

**AMENDMENT**

Applicants are in receipt of the Office Action dated October 13, 2005 of the above-referenced application. Please amend the application as follows:

**Amendments to the specification** begin on page 2 of this paper.

**Amendments to the claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks** begin on page 5 of this paper.